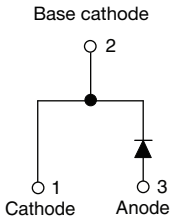
Ultrafast Rectifier, 30 A FRED Pt®

TO-220AC 2L



FEATURES

- Ultrafast and soft recovery
- Optimized forward voltage drop
- 175 °C maximum operating junction temperature
- Polyimide passivation
- Rugged design
- Good thermal performance
- AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Pb-free

e3

RoHS COMPLIANT

HALOGEN FREE

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	30 A
V_R	1200 V
V_F at I_F at 125 °C	2.05 V
t_{rr}	49 ns
T_J max.	175 °C
Package	TO-220AC 2L
Circuit configuration	Single

DESCRIPTION / APPLICATIONS

Ultrafast recovery rectifiers designed with optimized performance of forward voltage drop, recovery time, and soft recovery. Polyimide passivated, planar structure, and the platinum doped life time control guarantee, ruggedness, reliability characteristics, and solid value proposition for efficiency and thermal performance.

These devices are intended for use in boost stage in the AC/DC section of SMPS, high frequency output rectification of battery charger, inverters for solar inverters, or as freewheeling diodes in motor drive.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Repetitive peak reverse voltage	V_{RRM}		1200	V
Average rectified forward current	$I_{F(AV)}$	T_C = 100 °C, D = 0.50	30	A
Repetitive peak forward current	I_{FRM}		60	A
Non-repetitive peak surge current	I_{FSM}	T_C = 25 °C, t_p = 10 ms, sine wave	240	A
Operating junction and storage temperature	T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS (T_J = 25 °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	I_R = 500 µA	1200	-	-	V
Forward voltage	V_F	I_F = 30 A	-	2.15	2.68	V
		I_F = 30 A, T_J = 125 °C	-	2.05	2.45	V
Reverse leakage current	I_R	V_R = V_R rated	-	-	145	µA
		T_J = 125 °C, V_R = V_R rated	-	-	320	µA
Junction capacitance	C_T	V_R = 200 V	-	29	-	pF
Series inductance	L_S	Measured to lead 5 mm from package body	-	8	-	nH

DYNAMIC RECOVERY CHARACTERISTICS (T_J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	I_F = 1.0 A, dI_F/dt = 100 A/µs, V_R = 30 V		-	49	-	ns
		T_J = 25 °C	I_F = 30 A dI_F/dt = 100 A/µs V_R = 390 V	-	220	-	
		T_J = 125 °C		-	356	-	
Peak recovery current	I_{RRM}	T_J = 25 °C		-	8.2	-	A
		T_J = 125 °C		-	13.3	-	
Reverse recovery charge	Q_{rr}	T_J = 25 °C		-	900	-	nC
		T_J = 125 °C		-	2388	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction to case	R_{thJC}		-	-	0.8	°C/W
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	54	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth, and greased	-	-	0.4	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Maximum junction and storage temperature range	T_J, T_{Stg}		-55	-	175	°C
Marking device		Case style: TO-220AC 2L	30ETU12TH			

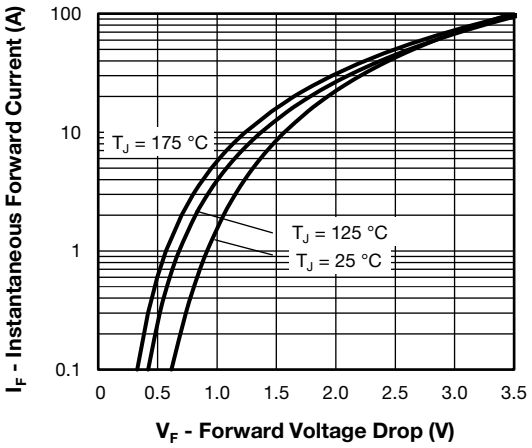


Fig. 1 - Typical Forward Voltage Drop Characteristics

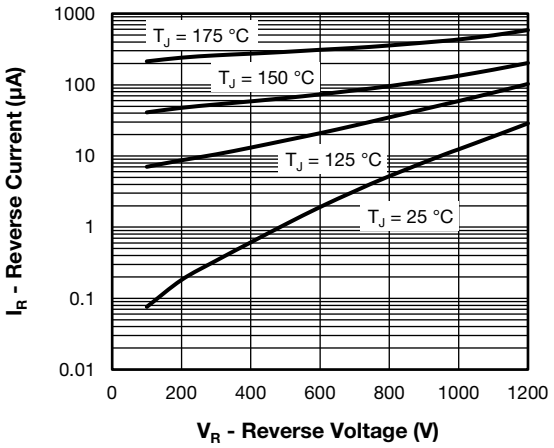


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

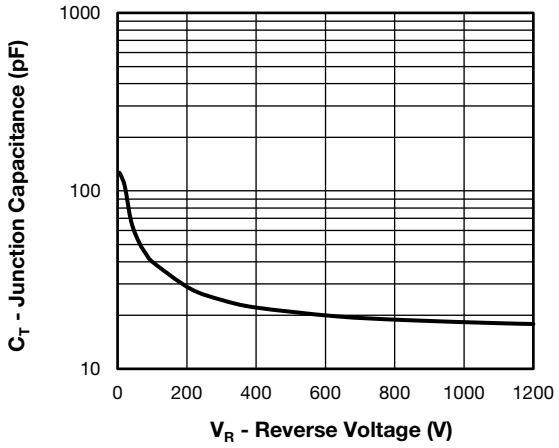


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

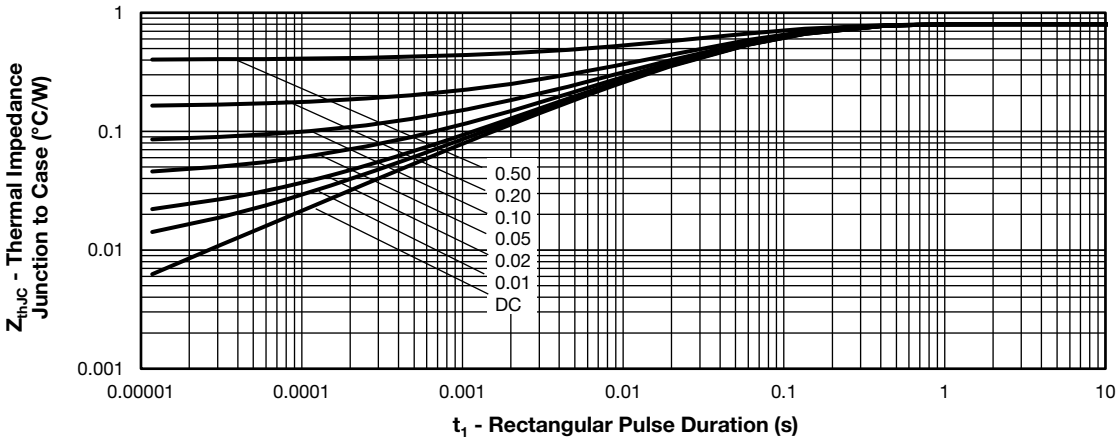


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

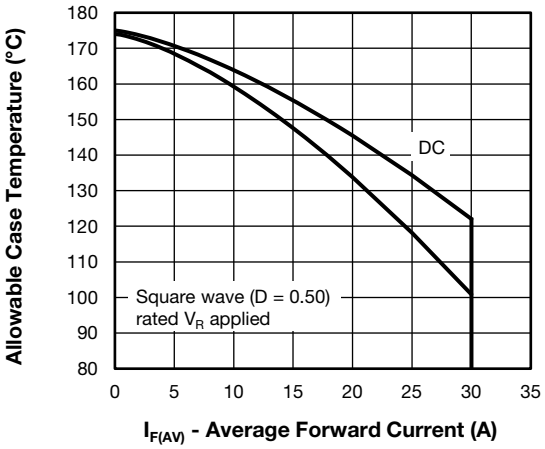


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

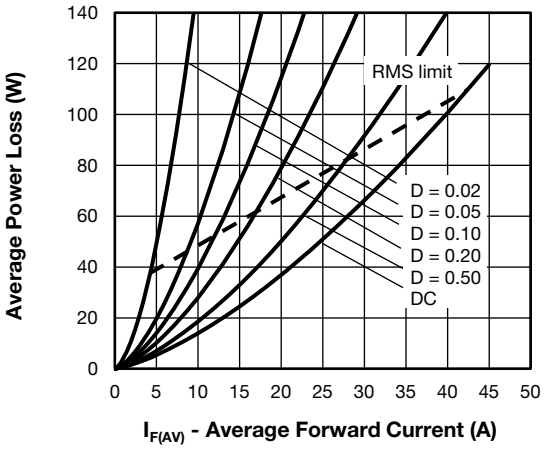


Fig. 6 - Forward Power Loss Characteristics

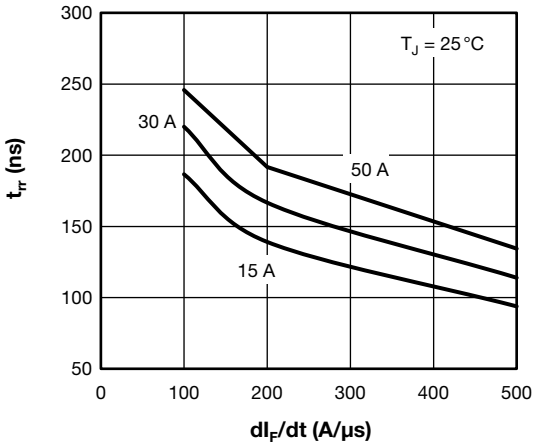


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

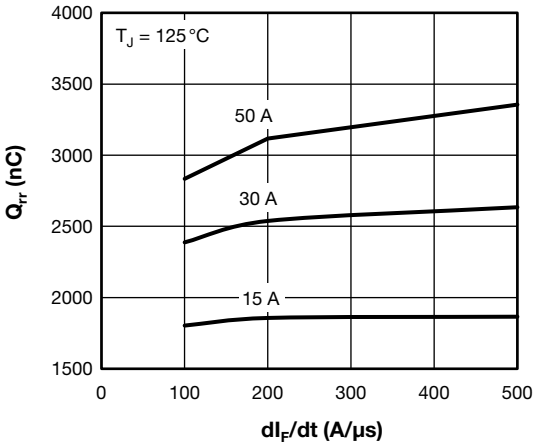


Fig. 10 - Typical Stored Charge vs. dI_F/dt

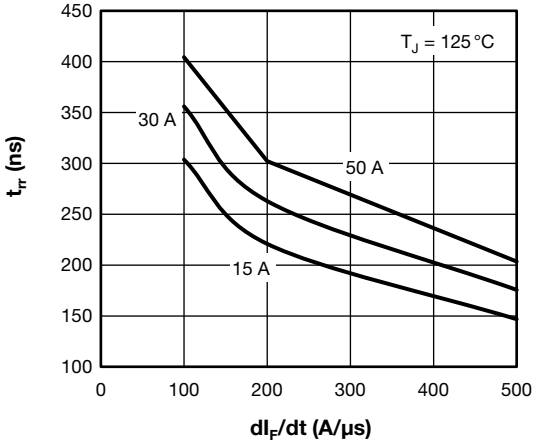


Fig. 8 - Typical Reverse Recovery Time vs. dI_F/dt

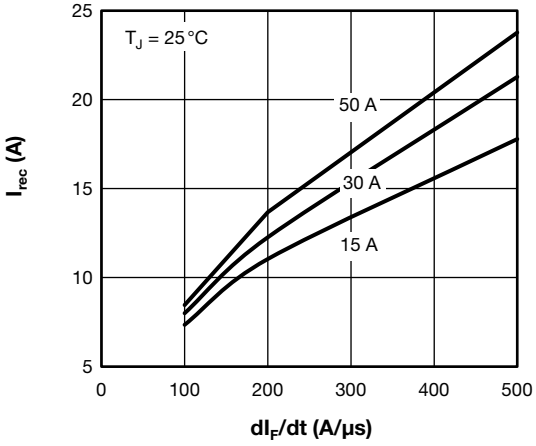


Fig. 11 - Typical Reverse Current vs. dI_F/dt

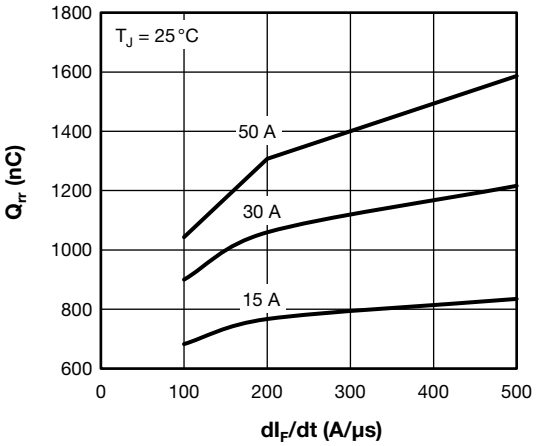


Fig. 9 - Typical Stored Charge vs. dI_F/dt

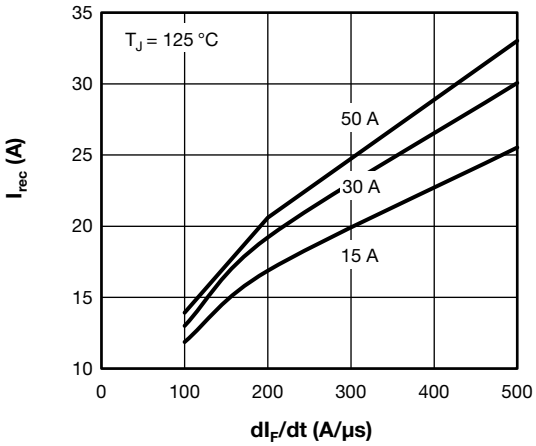
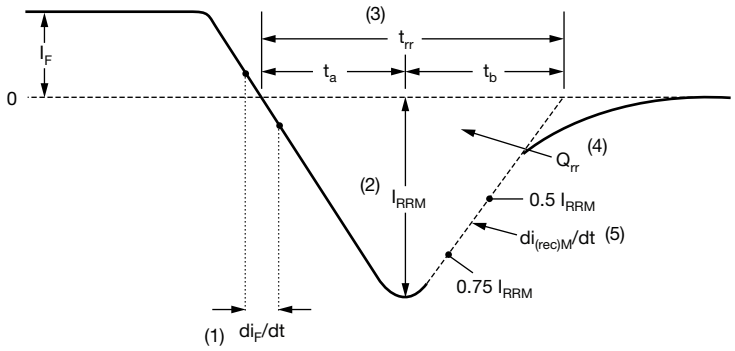


Fig. 12 - Typical Reverse Current vs. dI_F/dt



(1) di_F/dt - rate of change of current through zero crossing

(2) I_{RRM} - peak reverse recovery current

(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.

(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 13 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code

VS-	30	E	T	U	12	T	H	N3
1	2	3	4	5	6	7	8	9

- 1 - Vishay Semiconductors product
- 2 - Current rating 30 = 30 A
- 3 - E = single diode
- 4 - Package: T = TO-220AC
- 5 - U = ultrafast recovery
- 6 - Voltage rating (12 = 1200 V)
- 7 - T = True 2 pin TO-220
- 8 - H = AEC-Q101 qualified
- 9 - Environmental digit:

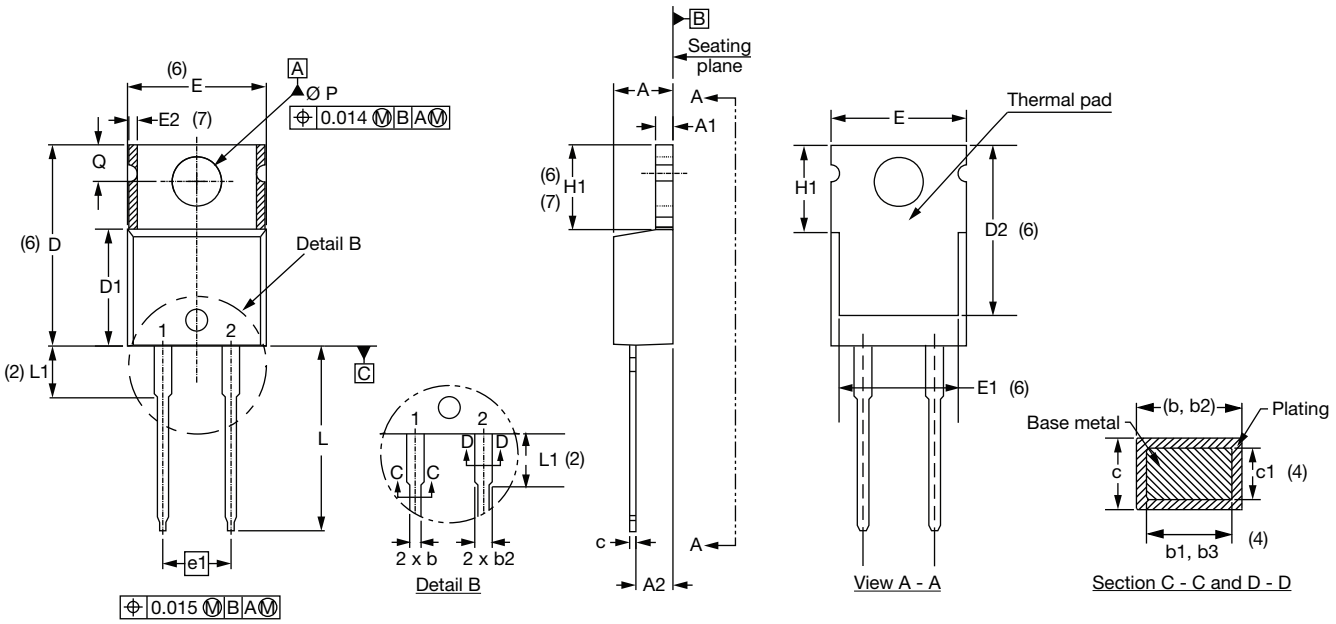
  N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	**QUANTITY PER TUBE**	**MINIMUM ORDER QUANTITY**	**PACKAGING DESCRIPTION**
VS-30ETU12THN3	50	1000	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS		
Dimensions	2L TO-220AC	www.vishay.com/doc?96069
Part marking information	2L TO-220AC	www.vishay.com/doc?95391

TO-220AC 2L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6
E	10.11	10.51	0.398	0.414	3, 6

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
e1	4.88	5.28	0.192	0.208	
H1	5.84	6.86	0.230	0.270	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
Ø P	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	

Notes

(1) Dimensioning and tolerancing as per ASME Y14.5M-1994
(2) Lead dimension and finish uncontrolled in L1
(3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
(4) Dimension b1, b3 and c1 apply to base metal only
(5) Controlling dimension: inches
(6) Thermal pad contour optional within dimensions E, H1, D2 and E1
(7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
(8) Outline conforms to JEDEC® TO-220, except D2, where JEDEC® minimum is 0.480"

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